

U.S. Patent Application Serial No. 10/044,986
Response dated July 28, 2004
Reply to OA of April 6, 2004

IN THE CLAIMS

Please amend claims 9-12 as follows:

Claims 1-8 (Canceled).

Claim 9 (Currently amended): A resin molded product which has a metal layer of a fine metal powder formed directly on the resin molded surface thereof, wherein tip ends of particles of the fine metal powder are impaled and forced into the resin molded surface and portions of the particles protruding on the surface of the resin molded product are deformed by the process of bringing a fine metal powder producing material into flowing contact with the resin molded surface and applying a vibration and/or an agitation to the resin molded product and the fine metal powder producing material.

Claim 10 (Currently amended): A resin molded product which has a metal layer of a fine metal powder formed directly on the resin molded surface thereof, ~~and a metal film formed on said metal layer~~ wherein tip ends of particles of the fine metal powder are impaled and forced into the resin molded surface and portions of the particles protruding on the surface of the resin molded product are deformed by the process of bringing a fine metal powder producing material into flowing contact with the resin molded surface and applying a vibration and/or an agitation to the resin molded product and the fine metal powder producing material,
and further comprising a metal plated film formed on said metal layer.

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Claim 11 (Currently amended): A resin molded product according to claim 9, wherein the particles of the fine metal powder have a ~~longer diameter~~ particle size of from 0.001 μm to 5 μm .

Claim 12 (Currently amended): A resin molded product according to claim 10, wherein the particles of the fine metal powder have a ~~longer diameter~~ particle size of from 0.001 μm to 5 μm .